PRODUCT CATALOGUE 2026

AOI, SPI and X-Ray Inspection

GÖPEL ELECTRONIC

Inline 3D CT and AXI X-ray, 3D AOI for SMD and THT assemblies, solder paste inspection and the PILOT software.



OVERVIEW

The GÖPEL range

Inspection solutions from GÖPEL electronic, Jena: inline 3D CT and 3D AXI X-ray inspection, 3D AOI for SMD and THT assemblies, stand-alone AOI, 3D solder paste inspection, assembly assistance for manual THT stations, and the PILOT software for networking and central verification of all inspection data.

	**Multi Line AXI** Inline 3D CT X-Ray Inspection System	Planar CT up to 8 µm Voxel · PCBs up to 810 × 535 mm and 25 kg · ASPECT™ Technology · No Compressed Air · Made in Germany
	**X Line · 3D** Inline 3D AXI X-Ray Inspection System	Double-Sided 3D X-Ray · Planar CT · MultiAngle Line Detectors · 5 s Handling Time · AXOI with AOI Module
	**Multi Line THT** AOI System for THT Assemblies	THT Components, THT Solder Joints and SMT Components · Double-Sided Inspection · MagicClick Programming · MES Ready
	**Multi Line SMD** 3D Inline AOI System for SMD Assemblies	Double-Sided Simultaneous Inspection · 3D, 15 µm/pixel · MagicClick in Minutes · Full 3D SPI Capable · MES Ready
	**Vario Line · 3D** 3D/2D/360° AOI System	Combined 3D/2D Inspection · Up to 360 Angled-View Directions · 12 µm Resolution · Up to 100 cm²/s · MagicClick
	**Basic Line · 3D** 2D/3D/360° Stand-Alone AOI System	Combined 3D/2D Inspection · Up to 360 Angled-View Directions · AI-Based MagicClick Programming · Also for 3D SPI · Seated or Standing
	**Multi Line SPI** 3D Inline Solder Paste Inspection	Fringe Projection 3D · 01005 Deposits · 0.2 µm Z Resolution · Program in < 10 min · Closed Loop to the Printer
	**Multi Line Assist** Assembly Assistance and Inspection for THT Stations	Visual Worker Guidance by Projection · Real-Time Camera Monitoring · 47 MP Colour Camera · MagicLight · MES Connection
PILOT CONNECT	**PILOT Connect** The Control Centre for Linking All Inspection Systems	AOI, AXI and SPI Networking · Central Database · Repair and Verification Stations · Process Statistics · MES and Traceability
	**PILOT Supervisor** Central Verification of Inspection Results from Several Systems	One Classifying Station for Several Lines · Third-Party AOI, AXI, SPI · Pass/Fail to the Conveyor · Central Database · MES

X-RAY INSPECTION

GÖPEL Multi Line AXI

Inline 3D CT X-Ray Inspection System

Planar CT up to 8 µm Voxel | PCBs up to 810 × 535 mm and 25 kg | ASPECT™ Technology | No Compressed Air | Made in Germany



OVERVIEW

The **GÖPEL Multi Line AXI** is a high-performance 3D CT X-ray system for the inline inspection of assembled PCBs, used directly in the production line or in test cells. Manual analysis of samples, field returns and prototypes is also possible.

It inspects small and light as well as large and heavy assemblies up to 810 × 535 mm and 25 kg by computed tomography, on a compact 1600 × 1660 mm footprint. Hidden defects under BGAs, QFNs, LGAs and LEDs, voids, THT solder penetration, bridges and solder beads are detected early and non-destructively.

KEY FEATURES

ASPECT™ technology
Adaptive Spot Precision Computer Tomography: maintenance-free sealed wide-angle microfocus source (65 W) with focal spot control for detailed, clear 3D CT images

55° oblique view without tilting
the wide beam angle gives excellent slice separation, combined with a 6.7-megapixel high-speed detector

On-the-fly CT
oblique images are captured while the axis system moves, for very short cycle times

Integrated AOI assistance camera
fiducials, code reading, colour navigation images and colour images for verification

PILOT software platform
the same programming platform as GÖPEL AOI, SPI and CCI systems; automatic void calculation, statistics and result export

Low-maintenance design
no compressed air needed; SMEMA, HERMES and MES plug-in connectivity

TECHNICAL SPECIFICATIONS

X-Ray Tube	Sealed microfocus tube, maintenance-free, focal spot control
Tube Parameters	130 kV, 500 µA, 65 W
Focal Spot	< 8 µm at 8 W
Detector	6.7-megapixel flat panel detector, 14-bit (16,384 grey levels)
Oblique Angle	up to 55°
Resolution / Field of View	8 µm: 22 × 19 mm, 10 µm: 28 × 24 mm, 15 µm: 42 × 36 mm, 20 µm: 56 × 48 mm, 25 µm: 70 × 60 mm
Image Capture	2D, 2.5D, 3D planar CT (on the fly)
3D Acquisition Time	up to 4 s per FOV at 120 projections
Max. PCB Size (L×W)	810 × 535 mm (larger on request with 2nd stopper)
Min. PCB Width	80 mm
Transport Weight	up to 25 kg
Component Clearance	top 85 mm, bottom up to 40 mm
Edge Support	3 mm (adjustable for carrier transport)
Test Functions	BGA, QFN, LGA, LED, THT, voiding, solder balls and more
Inline Interface	SMEMA, Siemens, HERMES; MES plug-ins
Transport Direction	left-right, right-left, left-left, right-right
Power Supply	230 V AC, 2 kVA
Compressed Air	none
Dimensions (W×D×H)	1600 × 1660 × 1720 mm
Weight	2.7 t
Leakage Radiation	< 0.5 µSv/h

Specifications according to GÖPEL. Subject to change without notice.

X-RAY INSPECTION

GÖPEL X Line · 3D

Inline 3D AXI X-Ray Inspection System

Double-Sided 3D X-Ray | Planar CT | MultiAngle Line Detectors | 5 s Handling Time | AXOI with AOI Module



OVERVIEW

The **GÖPEL X Line · 3D** is an inline AXI system for high-end inspection in PCB mass production, used for quality assurance of complex, high-value assemblies at high test speed. 3D X-ray inspection captures the top and bottom sides of the board in one continuous process.

Combined with an AOI module (AXOI), it also covers tasks X-ray alone cannot. Speed configurations and two image acquisition concepts adapt the system to the customer's test strategy; press-fit connectors are inspected with 3D planar CT as well.

KEY FEATURES

MultiAngle line detectors
bidirectional scanning line detectors capture 2D, 2.5D and 3D images simultaneously, without stop-and-go motion

Freely configurable 3D
image acquisition time and number of oblique projections are set to match the cycle time

Three-chamber principle
three internal conveyor modules for parallel loading, inspection and unloading; lead bulkheads keep X-rays inside during PCB change

intelliFLOW transport
automatically optimised transport parameters by PCB size, weight and friction

Digital maintenance concept
usage-based, predictive maintenance plans with component monitoring and maintenance logbook

Networking
MES plug-ins, HERMES, IPC CFX, ASYS Pulse

TECHNICAL SPECIFICATIONS

Detector	Ultra-high-speed line scan CCD detectors (MultiAngle Detector 3)
X-Ray Source	Sealed microfocus, 130 kV, max. 300 µA, max. 39 W, maintenance-free
Resolution	6–20 µm, freely selectable (typical 10–15 µm)
Grey-Scale Resolution	12 bit
Image Acquisition	2D, 2.5D, 3D (slice images with planar CT)
3D Inspection Speed	up to 100 cm^2/s
Axis System	X, Y, Z, 1 µm resolution
PCB Size	max. 450 × 400 mm, min. 60 × 50 mm
PCB Thickness	0.5–5 mm
PCB Weight	1.5 kg, optional 5 kg
Component Clearance	top max. 40 mm, bottom 65 mm
Transport Height	950 ± 25 mm or 850 ± 25 mm
Handling Time	approx. 5 s (parallel loading, inspection and unloading)
Solder Joint Defects	insufficient/excessive solder, short, open, voids, solder balls, lifted lead, head-in-pillow and more
Component Defects	position xy, rotation, missing, tombstone, billboard and more
Inline Interface	SMEMA, Siemens, HERMES; MES plug-ins, IPC CFX
Connection	230 V, 1-phase, 1.4 kVA, 6 bar compressed air
Dimensions (W×D×H)	1596 × 1540 × 1720 mm
Weight	2.6 t

Specifications according to GÖPEL. Subject to change without notice.

OPTICAL INSPECTION

GÖPEL Multi Line THT

AOI System for THT Assemblies

THT Components, THT Solder Joints and SMT Components | Double-Sided Inspection | MagicClick Programming | MES Ready



OVERVIEW

The **GÖPEL Multi Line THT** is an AOI system for THT assemblies. It inspects THT components, THT solder joints and SMT components, double-sided in the upper or lower transport module, with or without carrier.

MagicClick generates the AOI test program fully automatically in a few minutes, and flexible data interfaces connect the system to the line, to MES and to traceability systems.

KEY FEATURES

THT and SMT inspection
THT components, THT solder joints and SMT components in one system

Double-sided inspection
components from above and solder joints from below, in the upper or lower conveyor, with or without carrier

Three camera modules
2D orthogonal, 2D with 4 or 8 angled-view cameras, or 3D/2D with 15 µm/pixel

MagicClick
fully automatic AOI test program generation in a few minutes

Large and heavy boards
inspection area 540 × 450 mm, carriers up to 620 × 510 mm, up to 15 kg

Connectivity
SMEMA, HERMES, Siemens; MES and traceability interfaces

TECHNICAL SPECIFICATIONS

Camera Modules	2D AOI module (orthogonal, telecentric optics, 25 µm/pixel); 2D AOI module with angled view (4 or 8 oblique cameras, 25/35 µm/pixel); 3D AOI module (3D/2D, 15 µm/pixel)
Max. Inspection Height	2D modules up to 50 mm, 3D module 35 mm
Component Clearance	2D modules up to 140 mm, 3D module 40 mm (optional 50 or 60 mm)
Configurations	THT components from above, THT solder joints from below, or both, in the upper or lower conveyor
Max. Inspection Area	540 × 450 mm
Max. Carrier Size	up to 620 × 510 mm
Max. Transport Weight	15 kg
Transport System	conveyor belt for PCBAs with or without carrier
Transport Direction	left-right, right-left, left-left, right-right
Inline Interface	SMEMA, HERMES, Siemens, sensor
Power Supply	230 V AC / 2 kVA, compressed air 6 bar, < 20 l/h
Dimensions (W×D×H)	1150 × 1300 × 1800 mm
Weight	approx. 800 kg

Specifications according to GÖPEL. Subject to change without notice.

OPTICAL INSPECTION

GÖPEL Multi Line SMD

3D Inline AOI System for SMD Assemblies

Double-Sided Simultaneous Inspection | 3D, 15 µm/pixel | MagicClick in Minutes | Full 3D SPI Capable | MES Ready



OVERVIEW

The **GÖPEL Multi Line SMD** is a cost-effective 3D AOI system for inline use. Thanks to double-sided inspection, SMD assemblies can be inspected completely, from above, from below or on both sides simultaneously, in a single pass.

MagicClick generates the AOI test program fully automatically in a few minutes, the system can also be used as a full 3D solder paste inspection system, and flexible data interfaces connect it to the line, to MES and to traceability systems.

KEY FEATURES

Double-sided inspection
top side, bottom side or both sides simultaneously in the transport module

3D AOI module
orthogonal camera with telecentric optics and 3D sensors, 15 µm/pixel, 35 mm measurement height

MagicClick
fully automatic AOI test program generation in a few minutes, with PILOT AOI 7

Full 3D SPI
the same system can be used for 3D solder paste inspection

Multi Line platform
inspection area 540 × 450 mm, carriers up to 620 × 510 mm and 15 kg

Connectivity
SMEMA, HERMES, Siemens; MES and traceability interfaces

TECHNICAL SPECIFICATIONS

Camera Module	3D AOI: 3D/2D camera module, orthogonal camera, telecentric optics and 3D image capturing sensors
Resolution per Pixel	15 µm
Max. Inspection Height	35 mm
Component Clearance	40 mm
Configurations	inspection from above, from below, or both sides simultaneously
3D SPI	can be used as a full 3D solder paste inspection system
Max. Inspection Area	540 × 450 mm
Max. Carrier Size	up to 620 × 510 mm
Max. Transport Weight	15 kg
Transport	conveyor belt with or without carriers; left-right, right-left, left-left, right-right
Inline Interface	SMEMA, HERMES, Siemens, sensor
Power Supply	230 V AC / 2 kVA, compressed air 6 bar, < 20 l/h
Dimensions (W×D×H)	1150 × 1300 × 1800 mm
Weight	approx. 800 kg

Specifications according to GÖPEL. Subject to change without notice.

OPTICAL INSPECTION

GÖPEL Vario Line · 3D

3D/2D/360° AOI System

Combined 3D/2D Inspection | Up to 360 Angled-View Directions | 12 µm Resolution | Up to 100 cm²/s | MagicClick



OVERVIEW

The **GÖPEL Vario Line** and **Vario Line · 3D** are flexible inline AOI systems with maximum fault detection through combined 3D/2D technologies. An orthogonal camera with telecentric optics and 45° angled-view cameras with up to 360 inspection directions capture every solder joint.

With the 3D·ViewZ camera module, MagicClick generates the AOI test program automatically, and variable data interfaces integrate the system into the production process, MES and traceability.

KEY FEATURES

Maximum fault detection
excellent image quality of the orthogonal and angled-view cameras, up to 48 megapixels and 24-bit colour

Unique illumination
multi-spectral, multi-directional lighting

360° angled-view inspection
45° cameras with adapted focal plane, up to 360 inspection directions

3D measurement
camera module 3D·ViewZ in different speed variants, laser height measurement option

MagicClick
automated AOI test program generation in combination with 3D·ViewZ

MES / Industry 4.0
flexible interfaces, PILOT Connect fault analysis, data import from third-party inspection systems

TECHNICAL SPECIFICATIONS

2D Orthogonal Inspection	orthogonal camera, pixel-adapted telecentric optics, up to 48 megapixels, 24-bit colour
2D Angled-View Inspection	45° angled-view cameras with adapted focal plane, up to 360 inspection directions, up to 48 MP each
3D Measurement	camera module 3D·ViewZ (Vario Line 3D)
X/Y Resolution (2D)	12 µm
Illumination	multi-spectral, multi-directional
Component Clearance	above PCB 40 mm, below PCB 50 mm
Inspection Speed	up to 100 cm²/s
Max. Inspection Area	520 mm (900 mm optional) × 500 mm; 330 mm in 3-segment operation
Max. PCB Weight	5 kg
PCB Width	max. 510 mm, min. 80 mm (50 mm optional)
Transport	1 segment / 3 segments (optional); left-right, right-left, left-left, right-right
Inline Interface	SMEMA, Siemens, HERMES
Power Supply	230 V AC / 1.2 kVA, compressed air 6 bar, < 20 l/h
Dimensions (W×D×H)	1200 × 1450 × 1650 mm
Weight	approx. 950 kg

Specifications according to GÖPEL. Subject to change without notice.

OPTICAL INSPECTION

GÖPEL Basic Line · 3D

2D/3D/360° Stand-Alone AOI System

Combined 3D/2D Inspection | Up to 360 Angled-View Directions | AI-Based MagicClick Programming | Also for 3D SPI | Seated or Standing



OVERVIEW

The **GÖPEL Basic Line** and **Basic Line · 3D** are flexible stand-alone AOI systems with maximum fault detection through combined 3D/2D technologies, for prototypes, small series and offline inspection next to the line.

With the 3D·ViewZ camera module, MagicClick generates the test program automatically with AI support. Basic Line · 3D can also be used for 3D solder paste inspection, and variable configurations and data interfaces fit it into each manufacturing process.

KEY FEATURES

Maximum fault detection
orthogonal camera and 45° angled-view cameras, up to 48 megapixels and 24-bit colour, 360° angled-view inspection

Unique illumination
multi-spectral, multi-directional lighting

3D measurement
camera module 3D·ViewZ, optional with angled view and rotation drive; also for 3D solder paste inspection

AI-based MagicClick
automated test program generation with PILOT AOI

Variable configuration
extended inspection area, seated or standing work position

MES / Industry 4.0
flexible data interfaces, PILOT Connect fault analysis, data import from third-party inspection systems

TECHNICAL SPECIFICATIONS

2D Orthogonal Inspection	orthogonal camera, pixel-adapted telecentric optics, up to 48 megapixels, 24-bit colour
2D Angled-View Inspection	45° angled-view cameras with adapted focal plane, up to 360 inspection directions, up to 48 MP each
3D Measurement	camera module 3D·ViewZ, optional with angled view and rotation drive
Illumination	multi-spectral, multi-directional
Component Clearance	above PCB 40 mm, below PCB 100 mm
Inspection Area	510 × 350 mm (500 mm optional)
Work Position	seated or standing
Software	PILOT AOI with AI-based test program generation (MagicClick)
Power Supply	230 V AC / 1 kVA
Dimensions (W×D×H)	1133 × 1142 × 1430 mm
Weight	approx. 490 kg

Specifications according to GÖPEL. Subject to change without notice.

SOLDER PASTE INSPECTION

GÖPEL Multi Line SPI

3D Inline Solder Paste Inspection

Fringe Projection 3D | 01005 Deposits | 0.2 µm Z Resolution | Program in < 10 min | Closed Loop to the Printer



OVERVIEW

The **GÖPEL Multi Line SPI** is a cost-effective 3D inline solder paste inspection system on the Multi Line platform, ideal for small and medium-sized companies with high quality standards. It measures shape, area, volume, coplanarity, height, bridges and X/Y offset of every deposit.

High-precision fringe projection with double-sided projection gives 100% shadow-free measurement. Test programs are ready in less than 10 minutes, and a closed loop to the solder paste printer and the link to AOI/AXI data at the verification station close the process.

KEY FEATURES

Precise 3D measurement
shape, area, volume, coplanarity, height, bridges and X/Y offset, down to 01005 deposits

Fringe projection
8-megapixel camera at 180 frames/s with double-sided projection for 100% shadow-free measurement

Fast programming
test program generation typically under 10 minutes, offline programming, Gerber, CAD and ODB++ import

Process optimisation
repeatable measurement, statistical process control and closed loop to the printer

Linked data
SPI and AOI/AXI data combined at the verification station

Multi Line platform
inspection area 540 × 450 mm, carriers up to 620 × 510 mm and 15 kg

TECHNICAL SPECIFICATIONS

Measurements	shape, area, volume, coplanarity, height, bridges, X/Y offset
Smallest Solder Deposit	01005
Camera / Projector	8 megapixels, 180 frames/s, double-sided projection
X/Y Resolution	15 µm
Z Resolution	0.2 µm
Z Measuring Accuracy (on target)	up to 1 µm
Z Measuring Range	1000 µm
Inspection Speed	up to 51 cm²/s
Volume Repeatability	< 0.5% at ±3σ (calibration target), < 2% at ±3σ (PCB)
Gage R&R	< 10% at 6σ
Illumination	multi-spectral, multi-directional, for fiducial and barcode / 2D code recognition
Max. Board Deflection	±5 mm
Test Program Generation	typically < 10 minutes, offline programming
Data Import	Gerber (RS-274-X, RS-274-D), CAD, ODB++
Closed Loop	to the solder paste printer
Max. Inspection Area	540 × 450 mm
Max. Carrier Size	up to 620 × 510 mm
Max. Transport Weight	15 kg
Transport	conveyor belt with or without carriers; left-right, right-left, left-left, right-right
Inline Interface	SMEMA, HERMES, Siemens, sensor
Power Supply	230 V AC / 2 kVA, compressed air 6 bar, < 20 l/h
Dimensions (W×D×H)	1150 × 1300 × 1800 mm
Weight	approx. 800 kg

Specifications according to GÖPEL. Subject to change without notice.

ASSEMBLY ASSISTANCE

GÖPEL Multi Line Assist

Assembly Assistance and Inspection for THT Stations

Visual Worker Guidance by Projection | Real-Time Camera Monitoring | 47 MP Colour Camera | MagicLight | MES Connection



OVERVIEW

The **GÖPEL Multi Line Assist** guides operators at manual THT assembly stations and checks their work in real time. A projection unit shows the next step directly in the operator's field of vision, while a 47-megapixel colour camera monitors the board permanently.

It checks completeness, position, polarity, colour and labelling (OCR), either continuously during assembly or as a final inspection, and reports to MES.

KEY FEATURES

Visual worker guidance
assembly information projected into the operator's field of vision

Permanent optical monitoring
real-time inspection or final inspection at the end of assembly

Inspection functions
completeness, position and colour recognition, presence, positioning, polarity and labelling (OCR)

Three image field sizes
35, 50 or 75 mm lens, from 660 × 450 mm down to 0.5 mm recognition accuracy

MagicLight technology
top and side lighting for ideal contrast, minimal flashing, up to 50% interference light suppression, dimmable

MES / Industry 4.0
flexible data interfaces, data management and fault analysis via PILOT Connect

TECHNICAL SPECIFICATIONS

Module	MultiEyeS plus camera and projection module
Illumination	LED top and side lighting, MagicLight technology, 4000 K neutral white, approx. 2500 lux
Camera	47 megapixels, colour
Field of View / Resolution	35 mm lens: 660 × 450 mm, 81 µm/pixel, 0.7 mm; 50 mm: 475 × 320 mm, 58 µm/pixel, 0.6 mm; 75 mm: 300 × 200 mm, 37 µm/pixel, 0.5 mm recognition accuracy
Max. Inspection Height	100 mm
Monitor	24" or 32"
Projector	Full HD DLP laser projection unit
Integration	into an existing table, complete solution with height-adjustable table, or tabletop frame
Working Distance	1310 mm
Module Weight	45 kg (with side lighting and mounting brackets)
Power Supply	230 V AC / 0.5 kVA
Computer	Windows 11, i7, 32 GB RAM, 512 GB SSD, integrated

Specifications according to GÖPEL. Subject to change without notice.

INSPECTION SOFTWARE

GÖPEL PILOT Connect

The Control Centre for Linking All Inspection Systems

AOI, AXI and SPI Networking | Central Database | Repair and Verification Stations | Process Statistics | MES and Traceability



OVERVIEW

GÖPEL PILOT Connect provides a uniform interface and central data storage for the networked inspection systems of a production line. It manages the inspection results of the assemblies as well as the machine and operating data of the connected AOI, AXI and SPI systems.

At verification and repair stations, all data from the AOI, AXI and SPI systems is visible at a glance, so errors can be fully assessed. Statistical linking of the inspection data supports process analysis and optimisation.

KEY FEATURES

All data at a glance
AOI, AXI and SPI test data clearly shown at verification and repair stations

Targeted checking
automatic system checking of ambiguous errors with additional data capture

Process analysis and optimisation
statistical evaluation of the linked inspection data for monitoring the manufacturing process

Flexible databases
MySQL, MS SQL Server and Oracle Database

Common CAD data
imported CAD data shared by all systems for test program creation

Integrated user management
single log-on for all authorised computers and services; MES and traceability interfaces

FUNCTIONS

Connected Systems	GÖPEL AOI, AXI and SPI systems of a production line
Data Storage	central database: inspection results, machine and operating data
Databases	MySQL, MS SQL Server, Oracle Database
Workstations	verification and repair stations, statistics, mobile access
Interfaces	MES and traceability systems, integration with external systems
CAD Data	shared use of imported CAD data for test program creation
User Management	integrated, single log-on for all connected systems and modules
Data Maintenance	convenient data maintenance tools

Specifications according to GÖPEL. Subject to change without notice.

INSPECTION SOFTWARE

GÖPEL PILOT Supervisor

Central Verification of Inspection Results from Several Systems

One Classifying Station for Several Lines | Third-Party AOI, AXI, SPI | Pass/Fail to the Conveyor | Central Database | MES



OVERVIEW

The **GÖPEL PILOT Supervisor** software module allows central verification of test results from different inspection systems and production lines, including AOI, AXI and SPI systems from other manufacturers.

From a separate classifying station, one operator evaluates the results of several systems, so no extra verification workstations, PCs, software or licences are needed after the inspection systems in each line.

KEY FEATURES

Central verification
results from several inspection systems and lines on one central classifying station

Third-party integration
AOI, AXI and SPI systems from other manufacturers for fault display and statistical evaluation

Conveyor communication
Pass/Fail control of the verified PCB

High efficiency
system-wide and line-wide operation, central management of information and results

Flexible responsibilities
assignment of inspection systems and production lines to operators

All data in view
central database for all results, secure fault classification, central MES and traceability communication

FUNCTIONS

Function	central verification of inspection results from several inspection systems and production lines
Supported Systems	GÖPEL AOI, AXI and SPI, plus inspection systems from other manufacturers
Classification Station	one central workstation; no extra verification workstations (PC, software, licences) needed in the lines
Conveyor Communication	Pass/Fail control of the verified PCB
Database	all inspection results in a central database, including third-party systems
Organisation	flexible assignment of responsibilities for inspection systems and production lines
MES / Traceability	central communication with MES and traceability systems

Configuration, demo and quotation

InterElectronic is the GÖPEL partner for Hungary and Central Europe: application advice, sample tests, installation, training and service.

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